

ABSTRACT OF THE DISCLOSURE

A polishing apparatus polishes a workpiece such as a semiconductor wafer to a flat mirror finish. The polishing apparatus includes a storage cassette for storing workpieces to be polished, at least two polishing units each having at least a turntable with a polishing cloth mounted thereon and a top ring for supporting a workpiece and pressing the workpiece against the polishing cloth, and a cleaning unit for cleaning 10 a workpiece which has been polished by either one of the polishing units in such a state that the workpiece is removed from the top ring. The polishing apparatus further includes a transfer robot for transferring a workpiece between two of the storage cassette, the polishing units and the cleaning unit.

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